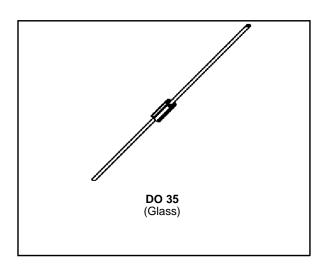
BAT 45

SMALL SIGNAL SCHOTTKY DIODE



DESCRIPTION

Metal to silicon junction diode primarly intended for UHF mixers and ultrafast switching applications.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	15	V
l _F	Forward Continuous Current	30	mA
I _{FSM}	Surge non Repetitive Forward Current	60	mA
T _{stg} T _j	Storage and Junction Temperature Range	- 65 to +150 - 65 to +125	္ခ <u>ိ</u> ဂိ
T∟	Maximum Temperature for Soldering during 10st Case	230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th (j-a)}	Junction-ambient*	400	°C/W

^{*} On infinite heatsink with 4mm lead length

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ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Тур.	Max.	Unit
V_{BR}	$T_{amb} = 25$ °C $I_R = 10\mu A$	15			V
V _F (1)	$T_{amb} = 25^{\circ}C$ $I_F = 1mA$			0.38	V
	$T_{amb} = 25$ °C $I_F = 10$ mA			0.5	
	$T_{amb} = 25$ °C $I_F = 30$ mA			1	
I _R (1)	$T_{amb} = 25$ °C $V_R = 6V$			0.1	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _{amb} = 25°C	$V_R = 1V$	f = 1MHz			1.1	pF
τ	T _{amb} = 25°C	$I_F = 20 \text{mA}$	Krakauer Method			100	ps
F (2)	T _{amb} = 25°C	f = 1GHz	_		6	7	dB

⁽¹⁾ Pulse test: $t_p \le 300 \mu s$ $\delta < 2\%$. (2) Noise figure test :

- intermediate frequency amplifier, tuned on 300MHz, has a noise figure 1.5dB

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

⁻ diode is inserted in a tuned stripline circuit

⁻ local oscillator frequency 1GHz

⁻ local oscillator power 1mW

Figure 1. Forward current versus forward voltage at different temperatures (typical values).

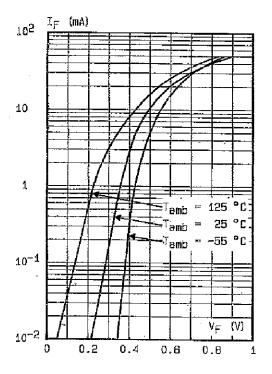


Figure 3. Reverse current versus junction temperature.

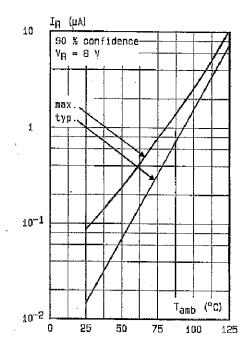


Figure 2. Forward current versus forward voltage (typical values).

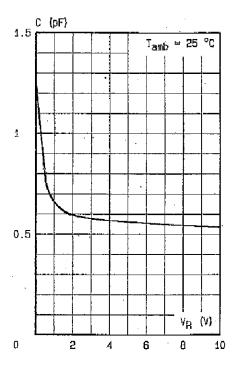
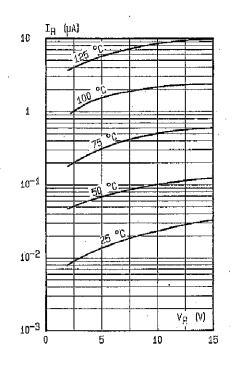
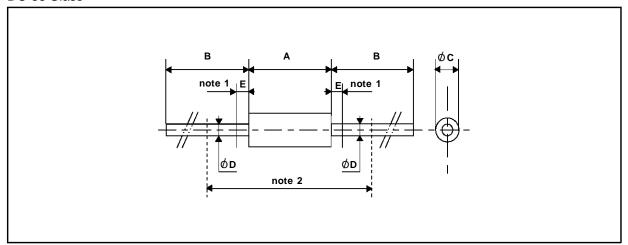


Figure 4. Reverse current versus continuous reverse voltage (typical values).



PACKAGE MECHANICAL DATA

DO 35 Glass



	DIMENSIONS						
REF.	REF. Millimeters		Inches		NOTES		
	Min.	Max.	Min.	Max.			
Α	3.050	4.500	0.120	0.117	1 - The lead diameter Ø D is not_controlled over zone E		
В	12.7		0.500				
ØC	1.530	2.000	0.060	0.079	2 - The minimum axial lengh within which the device may be placed with its leads bent at right angles is 0.59"(15 mm)		
ØD	0.458	0.558	0.018	0.022	phaced with its leads bent at right angles is 0.33 (13 min)		
Е		1.27		0.050			

Marking: clear, ring at cathode end. Weight: 0.15g

Cooling method: by convection and conduction

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